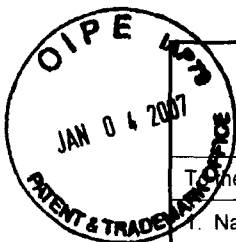


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Attorney Docket No.: 042390.P22467

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1. Name of conveying party(ies):
 Steven W. Johnston
 Chin-Chang Cheng
 Additional name(s) of conveying party(ies) attached?
 No Yes

2. Name and address of receiving party(ies):
 Name: Intel Corporation
 Internal Address: _____

3. Nature of Conveyance
 Assignment Merger
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 Other:
 Execution Date(s): _____

Street Address: 2200 Mission College Blvd
 City: Santa Clara State/Provence: CA Zip: 95052
 Country: USA
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4. Application number(s) or patent number(s) :
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6. Total number of applications and patents involved: 1

5. Name and address of party to whom correspondence concerning document should be mailed:
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Based on Form PTO-1595 as modified by BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP on 05/09/03

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Steven W. Johnston; Chin-Chang Cheng

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

Integrating A Bottomless Via To Promote Absorption Of Antisuppressor On Exposed Copper Surface And Enhance Electroplating Superfill On Noble Metals

the Declaration for which has been executed by the undersigned prior hereto or concurrently herewith, said patent application which can also be identified as follows (if necessary):

(I hereby authorize and request my attorney, associated with Customer Number 45209, to insert on the designated lines below, the filing date and application number of said application when known.)

United States Patent Application Number 11/479,399 filed on June 30, 2006

and in and to said application (nonprovisional or provisional) and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all nonprovisional applications claiming priority to said application, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its

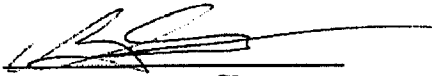
successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor please sign and Date below


Steven W. Johnston

12/28/06
(Today's Date)


Chin-Chang Cheng

12/20/06
(Today's Date)

INVENTOR 3

(Today's Date)